

## Lead (Pb) Free Product - RoHS Compliant

## FL810-03-80 High Power type LED

FL810-03-80 is an AlGaAs LED mounted on a lead frame and molded with super beam lens. On forward bias, it emits a band of visible light which peaks 810nm.

0 '6' '

◆Specifications

1) Product Name Super Flux mold type LED

2) Type No. FL810-03-80

3) Chip

(1) Chip Material GaAlAs

(2) Chip Dimension 800um\*800um

(3) Peak Wavelength 810nm typ.

4) Package

(1) Type Super Beam type LED

(2) Resin Material Epoxy Resin

(3) Lead Frame Silver Plated Cupper

## ♦ Absolute Maximum Ratings

7.62±0.2 cathode mark  96  7.25  a: anode c: cathode  0.75  5.08  6.48							

♦ Outer dimension (Unit: mm)

Item	Symbol	Maximum Rated Value Unit		Ambient Temperature	
Power Dissipation	Po	400 mW		Ta=25°C	
Forward Current	lF	250	mA	Ta=25°C	
Pulse Forward Current	lfp	2000	mΑ	Ta=25°C	
Reverse Voltage	Vr	10	V	Ta=25°C	
Operating Temperature	Topr	-30 ~ +85	°C	·	
Storage Temperature	Tstg	-30 ~ +100	°C		
Soldering Temperature	Tsol	265	°C		

<sup>‡</sup>Pulse Forward Current condition: Duty=1% and Pulse Width=10us.

## ◆Electro-Optical Characteristics [Ta=25°C]

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	VF	Ir=100mA		1.48	1.70	V
Pulsed Forward Voltage	VF	IFP=2A		3.0		V
Reverse Current	lr	Vr=10V			10	uA
Total Radiated Power	Po	Ir=100mA	20.0	24.0		mW
Radiant Intensity	ΙE	Ir=100mA		95		mW/sr
Peak Wavelength	λР	Ir=50mA	795	810	825	nm
Half Width	Δλ	I=50mA		25		nm
Viewing Half Angle	θ 1/2	I=50mA		±15		deg.
Rise Time	tr	lr=50mA		80		ns
Fall Time	tf	I=50mA		80		ns

<sup>‡</sup>Total Radiated Power is measured by Photodyne #500

<sup>‡</sup>Soldering condition: Soldering condition must be completed within 3 seconds at 265°C

<sup>‡</sup>Radiant Intensity is measured by Tektronix J-6512.